

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	2772	polish\$4 near15 (conductive-stud or bump or stud or ball)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2003/08/2 7 14:58	
2	BRS	L2	3515	polish\$4 near15 (conductive-stud or bump or stud or ball)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2003/08/2 7 14:58	
3	BRS	L3	63	1 and (wirebond\$4 or (wir\$4 adj bond\$4))	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2003/08/2 7 14:58	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
3	BRS	L4	7242	(polish\$4 or CMP and flatten\$4 or planar\$6) same (bump or stud or metal-stud or conductive-stud or conductive-bump or metal-bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/27 13:25	
4	BRS	L5	3380	4 and (reflow\$4 or reflow\$4 or heat\$4 or anneal\$4 or solder\$4 or reform\$4 or re-form\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/27 13:26	
5	BRS	L6	2102	4 and ((reflow\$4 or reflow\$4 or heat\$4 or anneal\$4 or solder\$4 or reform\$4 or re-form\$4) same (bump or stud or metal-stud or conductive-stud or conductive-bump or metal-bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/27 13:28	
6	BRS	L7	1615	4 and ((reflow\$4 or reflow\$4 or heat\$4 or anneal\$4 or solder\$4 or reform\$4 or re-form\$4) with (bump or stud or metal-stud or conductive-stud or conductive-bump or metal-bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/27 13:29	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
7	BRS	L8	537	7 and (wirebond or (wir\$4 adj bond\$4))	USPAT; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2003/08/27 13:29	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
3	BRS	L4	7242	(polish\$4 or CMP and flatten\$4 or planar\$6) same (bump or stud or metal-stud or conductive-stud or conductive-bump or metal-bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/27 13:25	
4	BRS	L5	3380	4 and (reflow\$4 or reflow\$4 or heat\$4 or anneal\$4 or solder\$4 or reform\$4 or re-form\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/27 13:26	
5	BRS	L6	2102	4 and ((reflow\$4 or reflow\$4 or heat\$4 or anneal\$4 or solder\$4 or reform\$4 or re-form\$4) same (bump or stud or metal-stud or conductive-stud or conductive-bump or metal-bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/27 13:28	
6	BRS	L7	1615	4 and ((reflow\$4 or reflow\$4 or heat\$4 or anneal\$4 or solder\$4 or reform\$4 or re-form\$4) with (bump or stud or metal-stud or conductive-stud or conductive-bump or metal-bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/27 13:28	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
6	BRS	L6	58210	(flat\$8 or planar\$4 or polish\$4 or CMP) same (bump or stud or ball)	USPAT; US-PGPUB; ; EPO; JPO; DERWENT; IBM-TDB	2003/08/26 16:04	
7	BRS	L7	3940	6 same (reflow\$4 or re-flow\$4 or solder\$4)	USPAT; US-PGPUB; ; EPO; JPO; DERWENT; IBM-TDB	2003/08/26 16:07	
8	BRS	L8	1072	7 and (wirebond\$4 or (wir\$4 adj bond\$4))	USPAT; US-PGPUB; ; EPO; JPO; DERWENT; IBM-TDB	2003/08/26 16:08	
9	BRS	L9	981	8 and (UBM or (under adj (bump or ball) or metal\$8))	USPAT; US-PGPUB; ; EPO; JPO; DERWENT; IBM-TDB	2003/08/26 16:09	